

**What is claimed is:**

1. Semiconductor device manufacturing equipment, comprising:

a plurality of interconnected chambers including a load-lock chamber, and at least one process chamber in which a wafer is to be processed;

a gate interposed between a pair of adjacent ones of said chambers and by which the chambers of said pair are connected, said gate constituting an open passageway along which a wafer is transferred between the chambers of said pair, and said gate defining doorways that each lead into a respective one of the chambers of said pair, the doorways each being sized to admit a semiconductor wafer therethrough; and

a gate valve disposed in said gate, said gate valve comprising a plurality of doors, and a driving unit operative to concurrently position said doors over said doorways, respectively, and thereby establish a plurality of discrete seals between the pair of chambers connected by the gate.

2. The semiconductor device manufacturing equipment according to claim 1, wherein said driving unit comprises a fluid-actuated cylinder connected to each of said doors.

3. The semiconductor device manufacturing equipment according to

claim 1, wherein said gate adjoins said process chamber.

4. The semiconductor device manufacturing equipment according to claim 1, wherein said plurality of chambers include a transfer chamber interposed between said load-lock chamber and said at least one process chamber, said transfer chamber having an internal space constituting said passageway, and comprising a robot operative to transfer a wafer along said passageway from said load-lock chamber to said at least one process chamber.

5. The semiconductor device manufacturing equipment according to claim 4, wherein said gate adjoins said transfer chamber and one of said process chambers.